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APPLICATION NO	D.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/688,354	-	10/17/2003	Ford B. Grigg	2269-5216.1US (99-0507.01		
24247	7590	03/14/2005		EXAM		
TRASK I	BRITT		WILSON, CHRISTIAN D			
P.O. BOX 2550				ART UNIT	PAPER NUMBER	
SALT LAKE CITY, UT 84110		01 84110		2829		
				DATE MAILED: 03/14/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)					
	10/688,354	GRIGG ET AL.					
Office Action Summary	Examiner	Art Unit					
	Christian Wilson	2829					
The MAILING DATE of this communication app Period for Reply							
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be timed within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	ely filed s will be considered timely. the mailing date of this communication. O (35 U.S.C. § 133).					
Status							
1) Responsive to communication(s) filed on							
,	action is non-final.						
•	Since this application is in condition for allowance except for formal matters, prosecution as to the ments is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims							
4) ☐ Claim(s) 1-15 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-15 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	vn from consideration.	· · ·					
Application Papers							
9)☐ The specification is objected to by the Examine 10)☒ The drawing(s) filed on 17 October 2003 is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11)☐ The oath or declaration is objected to by the Ex	a)⊠ accepted or b)⊡ objected drawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).					
Priority under 35 U.S.C. § 119							
12) ☐ Acknowledgment is made of a claim for foreign a) ☐ All b) ☐ Some * c) ☐ None of:  1. ☐ Certified copies of the priority documents 2. ☐ Certified copies of the priority documents 3. ☐ Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage					
Attachment(s)							
1) Notice of References Cited (PTO-892)	4) Interview Summary						
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 01092004,03012004, 112-12004,0915	Paper No(s)/Mail Da 5)	atent Application (PTO-152)					

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#### **DETAILED ACTION**

## Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1 13 and 15 are rejected under 35 U.S.C. 102(b) as being anticipated by Yaguchi *et al.*

Regarding claim 1, Yaguchi et al. (WO 97/01865) discloses a semiconductor device assembly [Figure 18G] comprising a carrier substrate 14, a first contact area 3 on the surface and at least one opening [Figure 18B], and solder mask 8 over at least a portion of the surface of the carrier substrate where the solder mask includes at least one opening through which the opening of the carrier and the contact area are exposed [Figure 18B].

Regarding claim 2, Yaguchi et al. further discloses a semiconductor die 1 including a bond pad 2 to an opposite surface of the carrier substrate with the bond pad exposed through the opening in the solder mask and carrier substrate [Figure 18B].

Regarding claim 3, Yaguchi et al. further discloses an intermediate conductive element 5 between the bond pad and contact area.

Regarding claim 4, Yaguchi *et al.* further discloses a thickness of a solder mask which exceeds the height of the intermediate conductive element which protrudes above the carrier substrate [Figure 18C].

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Regarding claim 5, Yaguchi et al. further discloses an encapsulant material 11 within the opening of the carrier substrate and solder mask.

Regarding claim 6, Yaguchi et al. further discloses an upper surface of the encapsulant material is level with the outer level of the solder mask [Figure 18E].

Regarding claim 7, Yaguchi *et al.* further discloses a distance between an uppermost portion of the intermediate conductive element and the outer surface of the solder mask is at least 25 µm [pg. 16, line 15 – pg. 17, line 10].

Regarding claim 8, Yaguchi *et al.* further discloses a bond wire and a thickness of the solder mask is equal to the sum of a distance a portion of a loop of the bond wire protrudes above the surface of the carrier substrate and about 25 µm [pg. 27, lines 3-12].

Regarding claim 9, Yaguchi *et al.* further discloses a conductive trace electrically connecting the first contact area and the second contact area [pg. 16, lines 1-10].

Regarding claim 10, Yaguchi *et al.* further discloses a second contact area 6 is exposed through an aperture of the solder mask.

Regarding claim 11, Yaguchi *et al.* further discloses a discrete conductive element protruding from the second contact area above the solder mask [Figure 18F].

Regarding claim 12, Yaguchi *et al.* further discloses at least half the height of the discrete conductive element protrudes above the outer surface of the solder mask [Figure 18G].

Regarding claim 13, Yaguchi *et al.* further discloses a solder mask and carrier substrate with substantially the same coefficient of thermal expansion [pg. 21, lines 20-25; pg. 27, lines 5-10].

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Regarding claim 15, Yaguchi *et al.* further discloses a solder mask with a thickness of 50  $\mu$ m to 100  $\mu$ m [pg. 27, lines 3-12].

### Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claim 14 is rejected under 35 U.S.C. 103(a) as being unpatentable over Yaguchi *et al.* in view of Matsumura *et al.*

Yaguchi et al. teaches the limitations of claim 1 as described above but does not teach the a solder mask comprising a cured photoimageable material. Matsumura et al. (US 5,181,984) teaches a solder mask comprising a photoimageable material 2. It would have been obvious to one of ordinary skill in the art to use the material of Matsumura et al. in the device of Yaguchi et al. since this material provides a solder mask that does not have air spaces which would allow solder to invade below the mask [column 1, lines 35-40].

#### Conclusion

- 5. A copy of the EAST search history is enclosed.
- 6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Christian Wilson whose telephone number is (571) 272-1886. The examiner can normally be reached on weekdays, 7:30 AM to 4 PM.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on (571) 272-1722. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (571) 272-2800.

Christian Wilson, Ph.D. Primary Examiner Art Unit 2829

**CDW**